

## TO-247-3

**SiC Power MOSFETs** 

Cactus Materials Power MOSFETs exceed power, efficiency and portability capabilities of standard silicon devices and are available in a variety of breakdown voltages (650V, 1200V, 1700V & 3300V) and current ratings. They have low on-resistance and low leakage in the blocking state. Fabricated on high-quality SiC epitaxial layers, our proprietary fabrication process includes carefully chosen annealing procedures to ensure a high-quality SiC-SiO $_2$  gate oxide dielectric layer. Doping profile neck region and edge termination ensure extremely low R $_{\scriptscriptstyle \text{ON}}$  and high breakdown voltage.

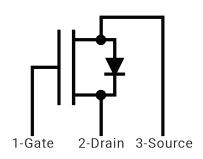
## **BENEFITS**

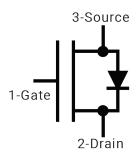
- ✓ Higher efficiency
- ✓ Reduced cooling
- ✓ Increased power
- √ Reduced system volume

## APPLICATIONS INCLUDE

Electromechanical power converters, DC to DC, AC to DC and DC to AC converters, switching power supplies, electric vehicles, hybrid vehicles, solar and wind energy power converters.







| Part Number      | Package  | Marking          |  |  |  |
|------------------|----------|------------------|--|--|--|
| CM-123-SCMB-065C | TO-247-3 | Cactus Materials |  |  |  |

| Maximum Ratings               |                      |   |          |          |            |       |
|-------------------------------|----------------------|---|----------|----------|------------|-------|
| *Characteristics              | Symbol               | Comments  | Min      | Тур      | Max        | Units |
| DC blocking voltage           | V <sub>DSmax</sub>   | T <sub>J</sub> =25°C  |          | 650      |            | V     |
| Gate input voltage range      | $V_{GS}$             | Recommended range<br>Dynamic  | -5<br>-5 |          | 15<br>18   | V     |
| Avalanche rating              | $V_{AVA}$            | T <sub>J</sub> =25°C  |          | 750      |            | V     |
| Pulsed drain current          | ID <sub>pulsed</sub> | $V_{GS}$ =15V; $V_{DS}$ =2V; $T_{J}$ =25°C<br>$V_{GS}$ =15V; $V_{DS}$ =2V; $T_{J}$ =175°C |          | 14<br>11 |            | А     |
| Continuous drain current      | ID                   | V <sub>GS</sub> =15V; T <sub>J</sub> =25°C<br>V <sub>GS</sub> =15V; T <sub>J</sub> =175°C |          | 10<br>8  |            | А     |
| Continuous drain power        | Р                    | $V_{GS}$ =15V; $T_J$ =25°C  |          | 100      |            | W     |
| Maximum- junction temperature | $T_{jmax}$           | Normal operation  During processing / soldering   |          |          | 175<br>250 | °C    |

| Electrical and Thermal Characteristics |                   |   |     |             |     |       |
|--|-------------------|---|-----|-------------|-----|-------|
| *Characteristics                       | Symbol            | Comments  | Min | Тур         | Max | Units |
| Gate threshold voltage                 | $V_{TH}$          | $V_{GS} = V_{DS}; I_{DS} = 5mA; T_J = 25^{\circ}C$<br>$V_{GS} = V_{DS}; I_{DS} = 5mA; T_J = 175^{\circ}C$ |     | 2.5<br>1.4  |     | V     |
| Gate leakage                           | I <sub>GSS</sub>  | $V_{GS} = 15V; V_{DS} = 0; T_J = 25^{\circ}C$<br>$V_{GS} = 15V; V_{DS} = 0; T_J = 175^{\circ}C$           |     | 7.2<br>47.1 |     | pA    |
| Drain leakage                          | I <sub>DSS</sub>  | $V_{DS}$ =600V; $V_{GS}$ =0; $T_J$ =25°C<br>$V_{DS}$ =600V; $V_{GS}$ =0; $T_J$ =175°C                     |     | 2.4<br>359  |     | nA    |
| Drain-source on-resistance             | R <sub>DSON</sub> | $V_{GS} = 15V; I_{DS} = 5A; T_J = 25^{\circ}C$<br>$V_{GS} = 15V; I_{DS} = 5A; T_J = 175^{\circ}C$         |     | 123<br>167  |     | mΩ    |
| Transconductance                       | $G_{\rm m}$       | $V_{DS}$ =10V; $I_{DS}$ =10A; $T_{J}$ =25°C<br>$V_{DS}$ =10V; $I_{DS}$ =10A; $T_{J}$ =175°C               |     | 5.3<br>5.8  |     | S     |
| Input capacitance                      | $C_{\rm ISS}$     | V <sub>GS</sub> =0V; V <sub>DS</sub> =200V;<br>f=1MHz; T <sub>J</sub> =25°C                               |     | 918         |     |       |
| Output capacitance                     | C <sub>oss</sub>  |   |     | 142         |     | pF    |
| Reverse transfer capacitance           | $C_{RSS}$         | 1-1141112, 1 <sub>J</sub> -20 0   |     | 5.6         |     |       |
| Stored energy at output                | E <sub>oss</sub>  |   |     | 5.7         |     |       |
| Turn on switching energy               | E <sub>on</sub>   | $V_{GS}$ =-5/15V; $V_{DS}$ =200V;<br>f=1MHz; $T_J$ =25°C  |     | 18.5        |     | Lц    |
| Turn off switching energy              | E <sub>OFF</sub>  |   |     | 5.8         |     |       |
| Rise time                              | $t_R$             | $V_{GS}$ =-5/15V; $V_{DS}$ =1kV; ID=10A;<br>RG=0 $\Omega$ ; $T_{J}$ =25°C                                 |     | 20          |     | nS    |
| Fall time                              | t <sub>F</sub>    | $V_{GS}$ =-5/15V; $V_{DS}$ =1kV; ID=10A;<br>RG=0 $\Omega$ ; $T_J$ =25°C                                   |     | 15          |     | nS    |
| Turn off delay time                    | $t_{_{D}}$        | $V_{GS}$ =-5/15V; $V_{DS}$ =200V; ID=10A; RG=0 $\Omega$ ; T $_{J}$ =25°C                                  |     | 10          |     | nS    |
| Gate Charge                            | $Q_{G}$           | $V_{GS}$ =-5/15V; $V_{DS}$ =200V; ID=10A; RG=0 $\Omega$ ; T $_{J}$ =25°C                                  |     | 10          |     | nS    |
| Internal gate resistance               | $R_{G}$           | f=1Mz; V <sub>AC</sub> =25mV; T <sub>J</sub> =25°C  |     | 5           |     | Ω     |
| Thermal resistance: Junction to Case   | $R_{JC}$          |   |     | 1.5         |     | °C/W  |

| Body diode characteristics |                        |   |     |            |     |       |
|----------------------------|------------------------|---|-----|------------|-----|-------|
| *Characteristics           | Symbol                 | Comments  | Min | Тур        | Max | Units |
| Diode forward voltage      | V <sub>F</sub>         | $I_F=3A; V_{GS}=0V; T_J=25^{\circ}C$<br>$I_F=3A; V_{GS}=0V; T_J=175^{\circ}C$         |     | 2.8<br>2.4 |     | V     |
| Pulsed diode current       | I <sub>s(pulsed)</sub> | $V_{GS} = 0V; V_{DS} = -3V; T_J = 25$ °C<br>$V_{GS} = 0V; V_{DS} = -3V; T_J = 175$ °C |     | 5<br>8     |     | А     |
| Reverse recovery time      | t <sub>rr</sub>        |   |     | 2          |     | ns    |
| Reverse recovery charge    | $Q_{rr}$               | $V_{DS}$ =0-200V; $V_{GS}$ =0V; $T_{J}$ =25°C   |     | 44         |     | nC    |

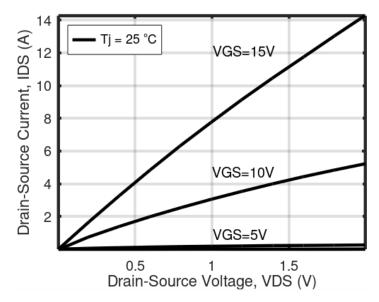


Figure 1: Output Characteristics TJ = 25°C.

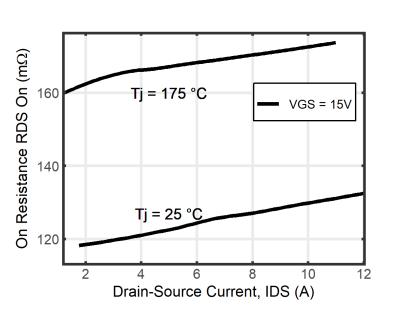


Figure 3: On-Resistance vs. Drain Current. For Various Temperatures

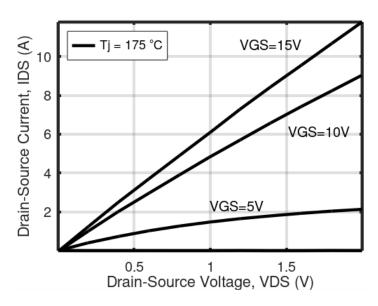


Figure 2: Output Characteristics TJ = 175°C.

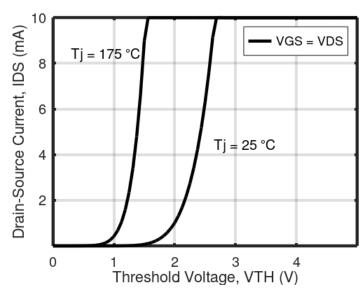
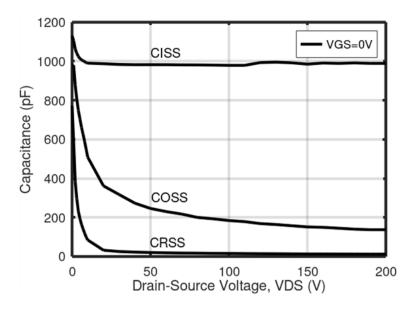


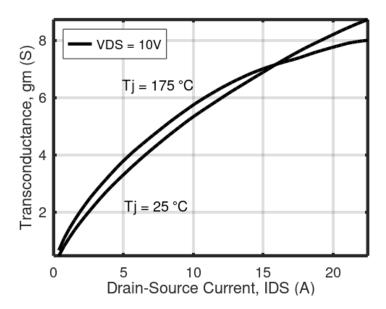
Figure 4: Drain Current vs. Threshold Voltage For Various Temperatures

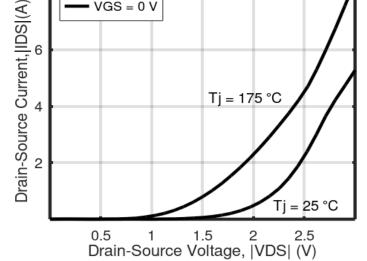


Drain-Source Current, IDS (A) VDS = 10VTj = 175 °C 30 20 10 Tj = 25 °C 0 10 12 Gate-Source Voltage, VGS (V)

Figure 5: Capacitances vs. Drain-Source Voltage (0 - 200V)

Figure 6: Transfer Characteristic





VGS = 0 V

Figure 7: Transconductance vs. Drain Current

Figure 8: Body Diode Characteristic For Various Temperatures

CAUTION: These devices are ESD sensitive. User proper handling procedures.

Disclaimer: The specifications provided are not a guarantee of component performance. It is essential to test components for their specific applications, as modifications may be required. Use of Cactus Materials components in life support systems and devices necessitates prior written approval from Cactus Materials.

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